



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



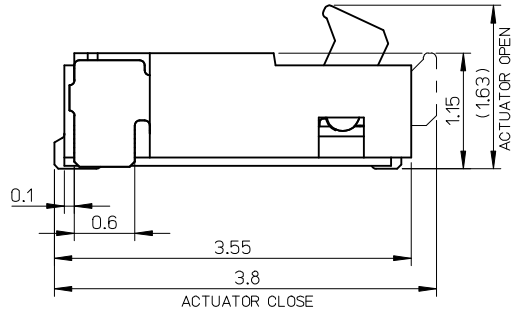
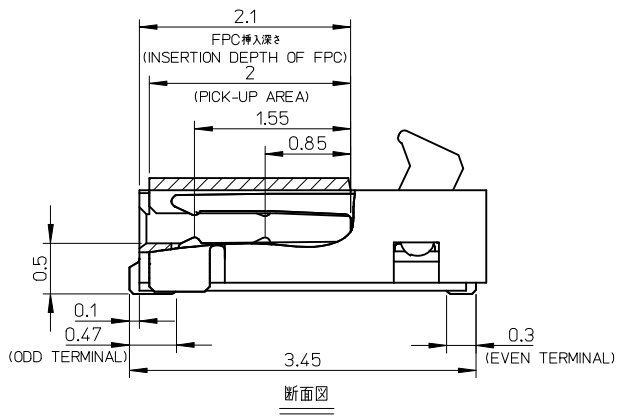
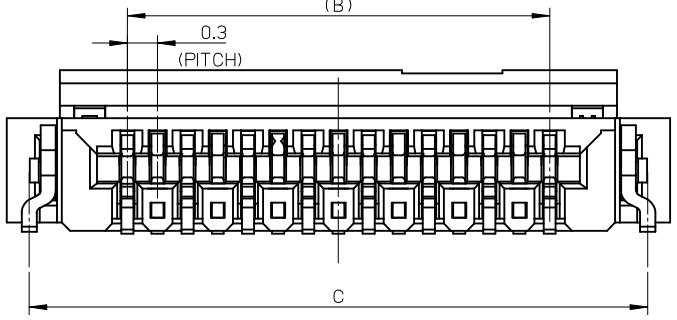
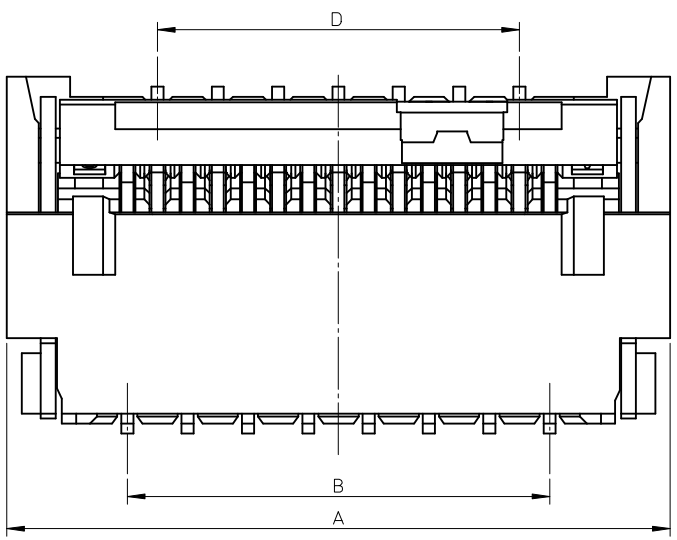
## Contact us

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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



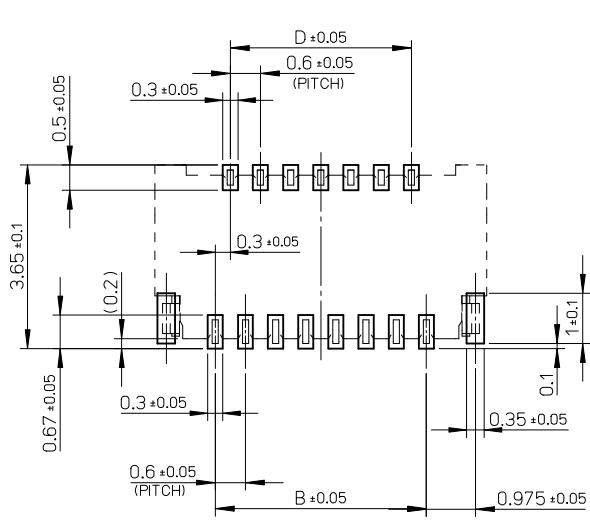


注記 NOTES:  
 1.材質 MATERIAL  
 ハウジング:LCP(液晶ポリマー)、白色、ガラス充填、UL94V-0  
 HOUSING:LIQUID CRYSTAL POLYMER,WHITE(NATURAL)  
 GLASS FILLED,UL94V-0  
 アクチュエータ:ポリアミド樹脂  
 黒色、ガラス充填、UL94HB  
 ACTUATOR: POLYAMIDE  
 BLACK GLASS FILLED,UL94HB  
 ターミナル:燐青銅 (t=0.12)  
 TERMINAL:PHOSPHOR BRONZE(t=0.12)  
 金具:燐青銅(t=0.15)  
 NAIL:PHOSPHOR BRONZE(t=0.15)  
 2.めっき仕様 PLATING  
 ターミナル TERMINAL  
 接点部:金めっき 0.1μm以上  
 CONTACT AREA: GOLD 0.1 MICROMETER MINIMUM  
 半田付け部:金めっき  
 SOLDER TAIL AREA: GOLD  
 下地めっき:ニッケル 1.0μm以上  
 UNDER PLATING:NICKEL 1.0 MICROMETER MINIMUM  
 金具 NAIL  
 錫めっき 1.0μm以上  
 TIN PLATING 1.0 MICROMETER MINIMUM  
 下地めっき:ニッケル 1.0μm以上  
 UNDER PLATING:NICKEL 1.0 MICROMETER MINIMUM  
 3.平坦度は、0.1ミリ以下とする。  
 TAILS COPLANARITY TO BE 0.1 MAXIMUM.  
 4.ELV及びRoHS適合品  
 ELV AND RoHS COMPLIANT  
 5.本製品は502598-\*\*91の端子材料変更品である。  
 THIS PRODUCT IS CHANGE OF TERMINAL MATERIAL FOR 502598-\*\*91.

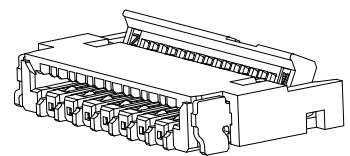
0.125	14.4	16.95	15	17.4	502598-5193	51
0.112	12.6	15.15	13.2	15.6	502598-4593	45
0.105	11.4	13.95	12.0	14.4	502598-4193	41
0.098	10.8	13.35	11.4	13.8	502598-3993	39
0.085	9	11.55	9.6	12	502598-3393	33
0.077	7.8	10.35	8.4	10.8	502598-2993	29
0.072	7.2	9.75	7.8	10.2	502598-2793	27
0.068	6.6	9.15	7.2	9.6	502598-2593	25
0.063	6	8.55	6.6	9	502598-2393	23
0.048	4.2	6.75	4.8	7.2	502598-1793	17
0.043	3.6	6.15	4.2	6.6	502598-1593	15
重さ (g) WEIGHT(g)	D	C	B	A	EMBOSSED PACKAGE オーダー番号 ORDER NO.	極数 CIRCUITS

CONNECTOR SERIES NO. 502598-\*\*21

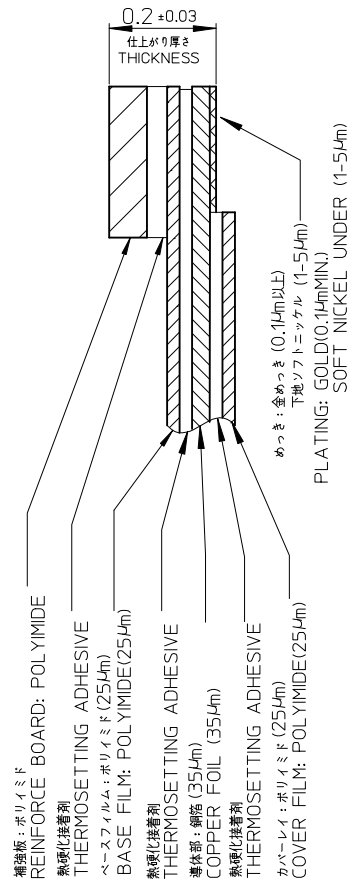
REVISED EC NO: J2014-0146 DRW:KINAGUMO 2013/07/25 CHKD:KATAHASHI 2013/08/30 APPR:YNOGAWA 2013/08/28	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY KMIYAHARA	DATE 2012/07/18	TITLE 0.3 FPC CONN. BACK FLIP HOUSING ASSY	
	10 OVER 30 UNDER	±0.25	CHECKED BY KTAKAHASHI	DATE 2012/07/18		
	30 OVER	±0.3	APPROVED BY KMORIKAWA	DATE 2012/08/01		
REV	ANGULAR	±1 °	MATERIAL NO.	DOCUMENT NO.	SHEET NO.	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-502598-003	
			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



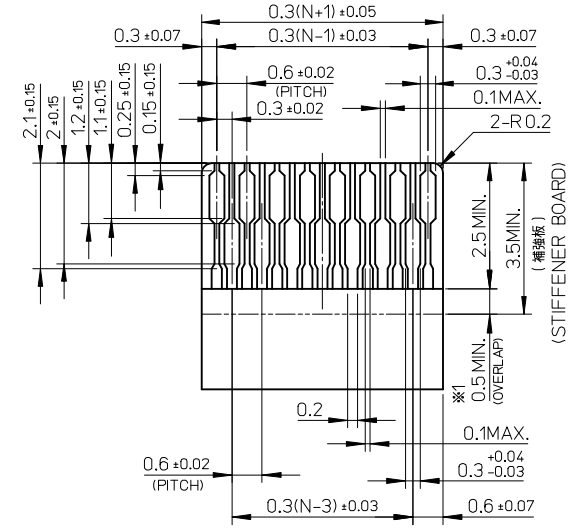
推奨基板寸法  
RECOMMENDED P.W.B. PATTERN LAYOUT  
マスク厚: 100 μm  
マスク開口率: 100%  
SCREEN THICKNESS: 100 μm  
SCREEN OPEN RATIO: 100%



ISO VIEW (参考)



FPC構成推奨仕様  
STRUCTURE OF FPC



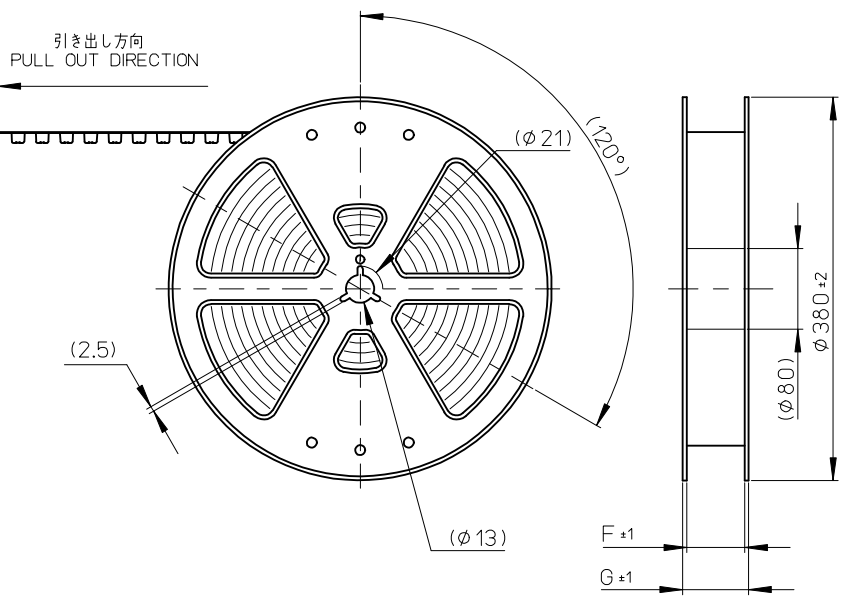
適合する金めっきFPC推奨寸法  
APPLICABLE FPC OF GOLD PATING  
RECOMMENDED DIMENSION

(仕上がり厚さ: 0.2±0.03)  
(THICKNESS: 0.2±0.03)

FPCについて:  
抜き方向は、導体側から補強板側を推奨致します。  
補強フィルム材質は、ポリイミドを推奨致します。  
接着剤は熱硬化接着剤を推奨致します。  
尚、接着剤の接点部への付着は導通不良の原因になりますので、  
染み出しが無い様、お願い致します。

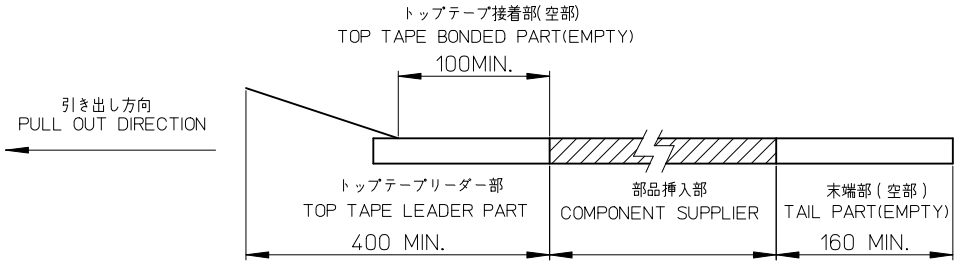
ABOUT FPC:  
RECOMMENDED PUNCHER DIRECTION:  
FROM CONDUCTOR SIDE TO STIFFNER FILM SIDE.  
RECOMMENDED MATERIAL:  
STIFFENER FILM: POLYIMIDE  
BONDING AGENT: THERMOSETTING AGENT  
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON  
ADHEREND BECAUSE THERE IS A POSSIBILITY THAT  
THE EXTRA ADHESIVE CAUSES THE DEFECT IN  
ELECTRICAL CONTINUITY.

REVISED EC NO: J2014-0146 DRWN: KINAGUMO 2013/07/25 CHKD: KAKAHASHI 2013/08/30 APPR: YNOGAWA 2013/08/28	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY KMIYAHARA	DATE 2012/07/18	TITLE 0.3 FPC CONN. BACK FLIP HOUSING ASSY			
		10 OVER 30 UNDER	±0.25	CHECKED BY KTAKAHASHI	DATE 2012/07/18				
		30 OVER	±0.3	APPROVED BY KMORIKAWA	DATE 2012/08/01				
REV	ANGULAR	±1 °	MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-502598-003		SHEET NO. 2 OF 2		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



注記)  
NOTES

1. 製品番号502598-\*\*-21の詳細寸法は、製品単体図面を参照下さい。  
IN THE PACKAGE PART NUMBER 502598-\*\*-21 DETAIL DIMENSIONS, SEE SALES DRAWING FOR CONNECTOR.
2. 梱包数量: 3000個/リール  
NUMBER OF CONNECTORS : 3000 PCS/REEL
3. リードテープ長さ  
LEAD TAPE LENGTH



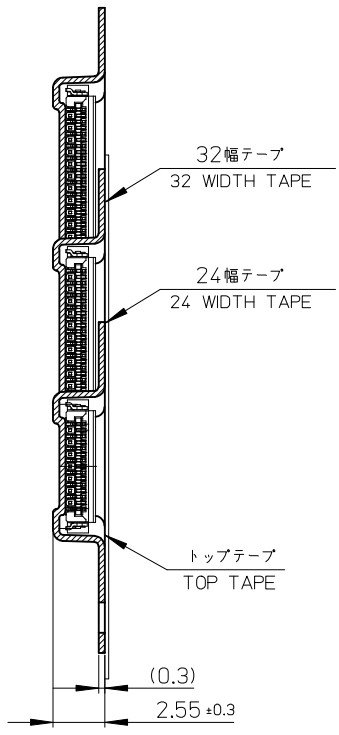
4. カバーテープの剥離強度については、IEC60286-3に準拠  
COVER TAPE PEEL FORCE IS DEFINED BY IEC 60286-3.
5. 材料  
MATERIAL  
キャリアテープ: ポリスチレン (PS)  
CARRIER TAPE: POLYSTYRENE (PS)  
トップテープ: ポリエチレンテレフタレート (PET)、他  
TOP TAPE : POLYETHYLENE TELEPHTHALATE (PET), OTHERS  
リール: ポリスチレン (PS)  
REEL: POLYSTYRENE (PS)
6. ELV及RoHS適合品  
ELV AND RoHS COMPLIANT
7. 本製品は502598-\*\*-91の端子材料変更品である。  
THIS PRODUCT IS CHANGE OF TERMINAL MATERIAL FOR 502598-\*\*-91.

REVISED	EC NO: J2014-0146	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
	DRWN:KNAGUMO 2013/07/25	10 UNDER	± ---	MM ONLY		---	METRIC	⊙ □	
	CHKD:KTAKAHASHI 2013/08/30	10 OVER 30 UNDER	± ---	DRAWN BY	DATE	TITLE			
	APPR:YNOGAWA 2013/08/28	30 OVER	± ---	KMIYAHARA	2012/07/18	0.3 FPC CONN. BACK FLIP TAPING PACKAGE (502598-**-21 SERIES)			
DESCRIPTION	ANGULAR	±1 °	CHECKED BY	DATE	<b>molex</b>				
REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY	DATE					DOCUMENT NO.
B			KMORIKAWA	2012/08/01	SD-502598-004		1 OF 2		
			SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
			A3						

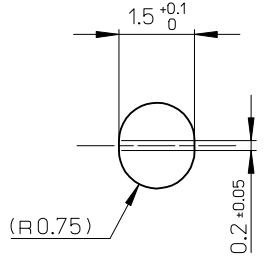
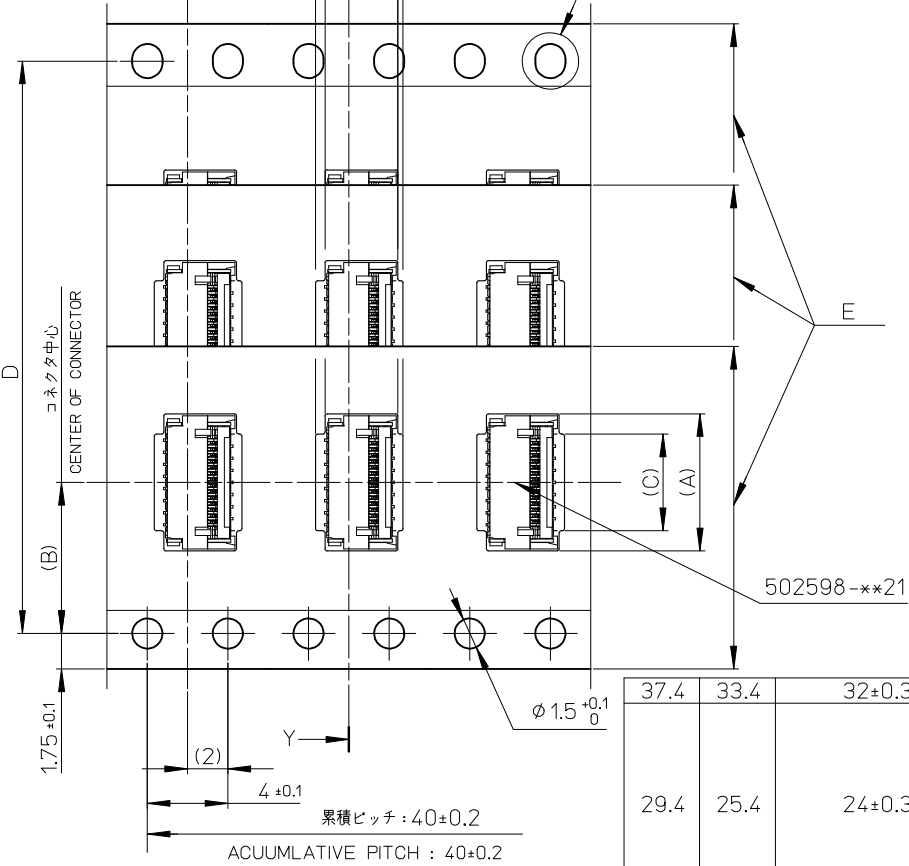
10 9 8 7 6 5 4 3 2 1

引き出し方向  
PULL OUT DIRECTION

Y  
8 ± 0.1  
(PITCH)  
(2.43)  
(4.34)  
(3.61)



断面 Y-Y  
SECTION Y-Y



T部詳細  
DETAIL T

37.4	33.4	32 ± 0.3	28.4	15.7	14.2	17.6	502598-5193	51
29.4	25.4	24 ± 0.3	+-	13.9	11.5	15.8	502598-4593	45
				12.7		14.6	502598-4193	41
				12.1		14	502598-3993	39
				10.3		12.2	502598-3393	33
				9.1		11	502598-2993	29
				8.5		10.4	502598-2793	27
				7.9		9.8	502598-2593	25
21.4	17.4	16 ± 0.3	+-	7.3	7.5	9.2	502598-2393	23
				5.5		7.4	502598-1793	17
				4.9		6.8	502598-1593	15
G	F	E キャリアテープ幅 EMBOSSED TAPE WIDTH	D	C	B	A	製品番号 MATERIAL NO.	極数 CIRCUITS

REVISED EC NO: J2014-0146 DRW: KIKAGUMO 2013/07/25 CHKD: TAKAHASHI 2013/08/30 APPR: YNOGAWA 2013/08/28	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	± ---	DRAWN BY KMIYAHARA	DATE 2012/07/18	TITLE 0.3 FPC CONN. BACK FLIP TAPING PACKAGE (502598-**-21 SERIES)			
		10 OVER 30 UNDER	± ---	CHECKED BY KTAKAHASHI	DATE 2012/07/18				
		30 OVER	± ---	APPROVED BY KMORIKAWA	DATE 2012/08/01				
REV	DESCRIPTION	ANGULAR ± 1 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO.	SEE TABLE	DOCUMENT NO. SD-502598-004	SHEET NO. 2 OF 2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	

9 8 7 6 5 4 3 2